

Appl. No. 10/709,427
Amdt. dated October 26, 2005
Reply to Office action of 09/28/2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1 (original): A chip-packaging with bonding options having a plurality of package
5 substrates, comprising:

a first package substrate;

a second package substrate;

a chip mounted on first package substrate, the chip comprising a plurality of the
bonding pads, one bonding pad being connected to the first package
10 substrate, another bonding pad being connected to the second package
substrate; and

a lead frame connected to one bonding pad.

2 (original): The chip-packaging of the claim 1 wherein the first package substrate is
15 applied to a high voltage or a low voltage and the second package substrate is
applied to a high voltage or a low voltage.

3 (original): The chip-packaging of the claim 2 wherein the high voltage is the voltage of
the power supply and the low voltage is the ground voltage.

20 4 (original): The chip-packaging of the claim 1 wherein the lead frame is connected to
one pin of the chip-packaging.

5 (original): The chip-packaging of the claim 4 wherein the pin is connected to a high
25 voltage, a low voltage, or an input/output signal.

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6 (original): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate have different voltages.

7 (original): The chip-packaging of the claim 1 wherein the first package substrate extends outside the chip and the second package substrate surrounds the chip.
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8 (original): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate substantially approximate each of a plurality of the bonding pads.

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9-18 (cancelled).